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Kind regards,

Team Nexperia

74HC165; 74HCT165

8-bit parallel-in/serial out shift register

Rev. 4 — 28 December 2015

Product data sheet

1. General description

The 74HC165; 74HCT165 is an 8-bit serial or parallel-in/serial-out shift register. The device features a serial data input (DS), eight parallel data inputs (D0 to D7) and two complementary serial outputs (Q7 and $\overline{Q7}$). When the parallel load input ($\overline{PL}$) is LOW the data from D0 to D7 is loaded into the shift register asynchronously. When $\overline{PL}$ is HIGH data enters the register serially at DS. When the clock enable input ($\overline{CE}$) is LOW data is shifted on the LOW-to-HIGH transitions of the CP input. A HIGH on $\overline{CE}$ will disable the CP input. Inputs include clamp diodes, this enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Asynchronous 8-bit parallel load
- Synchronous serial input
- Complies with JEDEC standard no. 7A
- Input levels:
 - ◆ For 74HC165: CMOS level
 - ◆ For 74HCT165: TTL level
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Applications

- Parallel-to-serial data conversion

4. Ordering information

Table 1. Ordering information

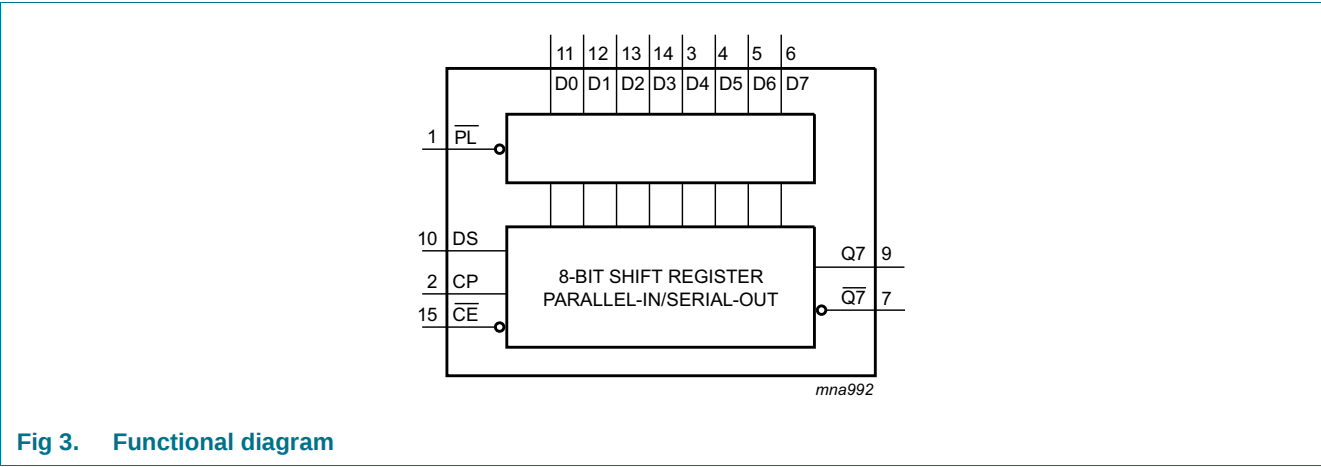
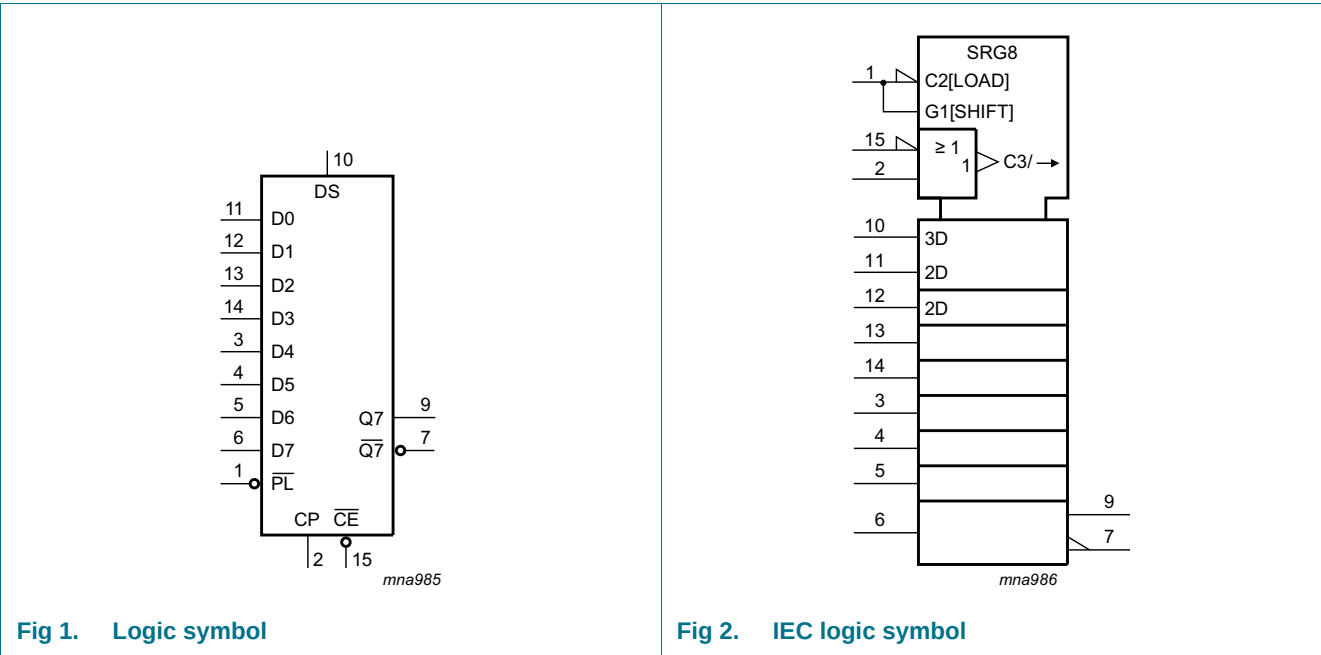
Type number	Package			
	Temperature range	Name	Description	Version
74HC165D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT165D				
74HC165DB	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT165DB				



Table 1. Ordering information ...continued

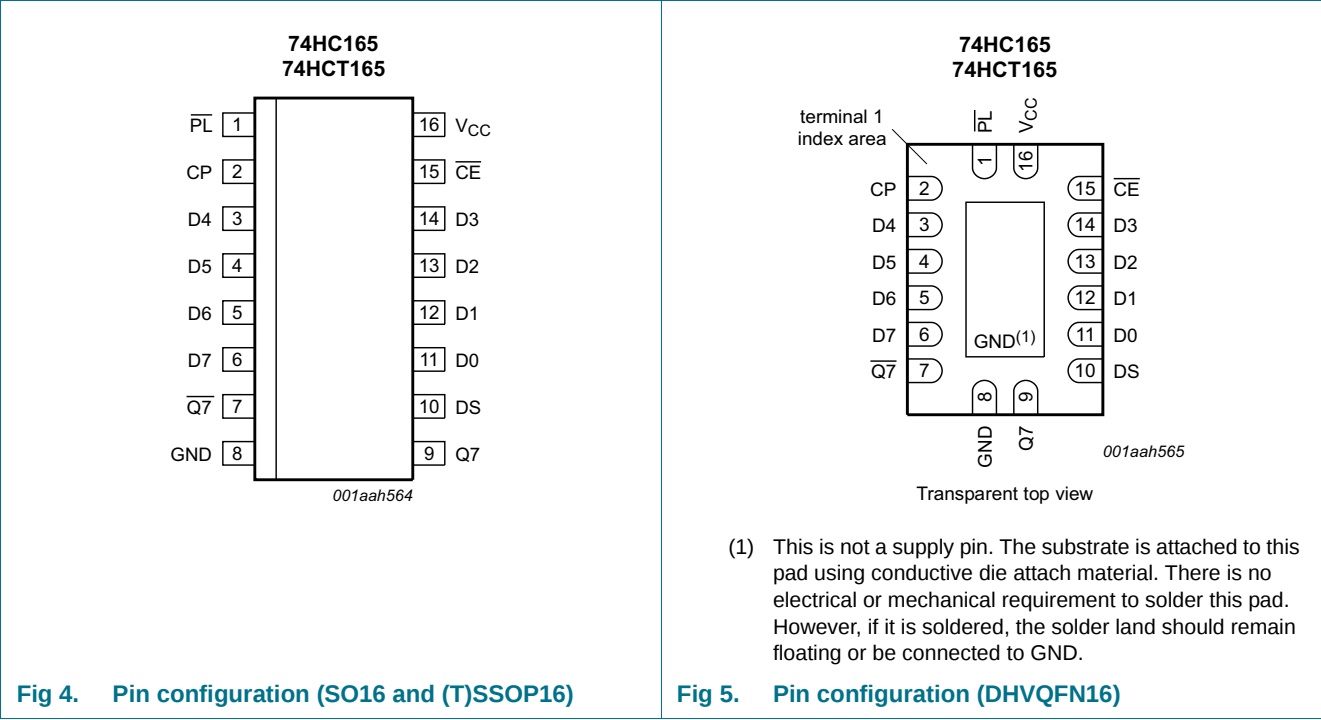
Type number	Package			
	Temperature range	Name	Description	Version
74HC165PW	−40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT165PW				
74HC165BQ	−40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
74HCT165BQ				

5. Functional diagram



6. Pinning information

6.1 Pinning



6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
PL	1	asynchronous parallel load input (active LOW)
CP	2	clock input (LOW-to-HIGH edge-triggered)
Q7	7	complementary output from the last stage
GND	8	ground (0 V)
Q7	9	serial output from the last stage
DS	10	serial data input
D0 to D7	11, 12, 13, 14, 3, 4, 5, 6	parallel data inputs (also referred to as Dn)
CE	15	clock enable input (active LOW)
VCC	16	positive supply voltage

7. Functional description

Table 3. Function table^[1]

Operating modes	Inputs					Qn registers		Outputs	
	PL	CE	CP	DS	D0 to D7	Q0	Q1 to Q6	Q7	Q7
parallel load	L	X	X	X	L	L	L to L	L	H
	L	X	X	X	H	H	H to H	H	L
serial shift	H	L	↑	l	X	L	q0 to q5	q6	q6
	H	L	↑	h	X	H	q0 to q5	q6	q6
	H	↑	L	l	X	L	q0 to q5	q6	q6
	H	↑	L	h	X	H	q0 to q5	q6	q6
hold "do nothing"	H	H	X	X	X	q0	q1 to q6	q7	q7
	H	X	H	X	X	q0	q1 to q6	q7	q7

- [1] H = HIGH voltage level;
h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition;
L = LOW voltage level;
l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition;
q = state of the referenced output one set-up time prior to the LOW-to-HIGH clock transition;
X = don't care;
↑ = LOW-to-HIGH clock transition.

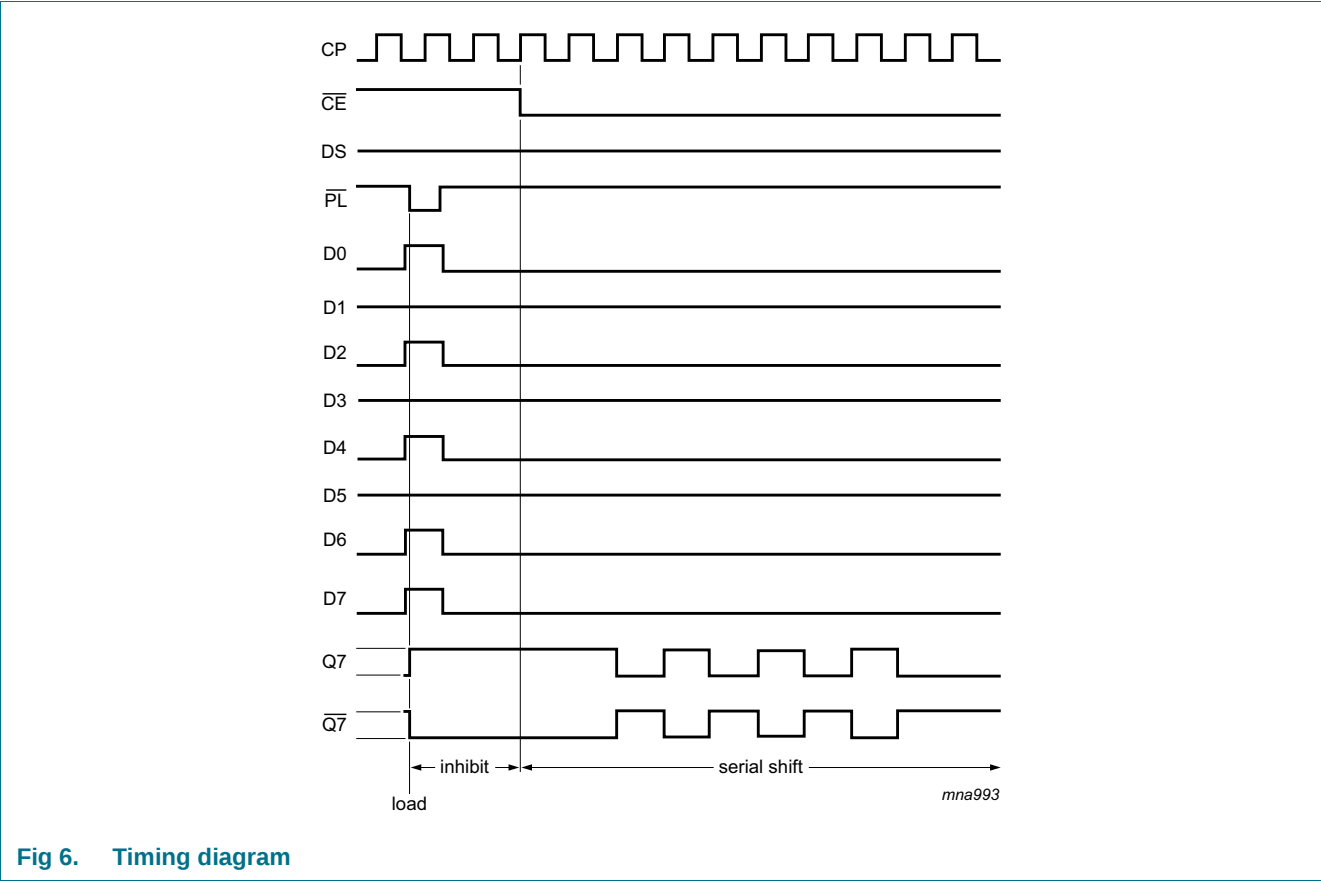


Fig 6. Timing diagram

8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7	V
I_{IK}	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$ [1]	-	± 20	mA
I_{OK}	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$ [1]	-	± 20	mA
I_O	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	± 25	mA
I_{CC}	supply current		-	50	mA
I_{GND}	ground current		-50	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40\text{ °C}$ to $+125\text{ °C}$			
		SO16 package [2]	-	500	mW
		(T)SSOP16 package [3]	-	500	mW
		DHVQFN16 package [4]	-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] P_{tot} derates linearly with 8 mW/K above 70 °C.

[3] P_{tot} derates linearly with 5.5 mW/K above 60 °C.

[4] P_{tot} derates linearly with 4.5 mW/K above 60 °C.

9. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC165			74HCT165			Unit
			Min	Typ	Max	Min	Typ	Max	
V_{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V_I	input voltage		0	-	V_{CC}	0	-	V_{CC}	V
V_O	output voltage		0	-	V_{CC}	0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	-	+125	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	-	-	-	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	-	-	-	ns/V

10. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC165										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = –20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = –20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = –20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = –4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	I _O = –5.2 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
		V _I = V _{IH} or V _{IL}								
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
I _I	input leakage current	I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
		V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1	-	±1	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	-	80	-	160	μA
C _I	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT165										
V _{IH}	HIGH-level input voltage	V _{CC} = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = –20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = –4.0 mA	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V								
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I _I	input leakage current	V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1	-	±1	μA

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0$ V	-	-	8.0	-	80	-	160	μ A
ΔI_{CC}	additional supply current	per input pin; $V_I = V_{CC} - 2.1$ V; other inputs at V_{CC} or GND; $V_{CC} = 4.5$ V to 5.5 V								
		Dn and DS inputs	-	35	126	-	157.5	-	171.5	μ A
		CP $\overline{CE}$, and $\overline{PL}$ inputs	-	65	234	-	292.5	-	318.5	μ A
C_I	input capacitance		-	3.5	-	-	-	-	-	pF

11. Dynamic characteristics

Table 7. Dynamic characteristicsGND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 12](#)

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC165										
t _{pd}	propagation delay	CP or $\overline{CE}$ to Q7, $\overline{Q7}$; see Figure 7 [1]								
		V _{CC} = 2.0 V	-	52	165	-	205	-	250	ns
		V _{CC} = 4.5 V	-	19	33	-	41	-	50	ns
		V _{CC} = 6.0 V	-	15	28	-	35	-	43	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	16	-	-	-	-	-	ns
		$\overline{PL}$ to Q7, $\overline{Q7}$; see Figure 8								
		V _{CC} = 2.0 V	-	50	165	-	205	-	250	ns
		V _{CC} = 4.5 V	-	18	33	-	41	-	50	ns
		V _{CC} = 6.0 V	-	14	28	-	35	-	43	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	15	-	-	-	-	-	ns
		D7 to Q7, $\overline{Q7}$; see Figure 9								
		V _{CC} = 2.0 V	-	36	120	-	150	-	180	ns
		V _{CC} = 4.5 V	-	13	24	-	30	-	36	ns
		V _{CC} = 6.0 V	-	10	20	-	26	-	31	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	11	-	-	-	-	-	ns
t _t	transition time	Q7, $\overline{Q7}$ output; see Figure 7 [2]								
		V _{CC} = 2.0 V	-	19	75	-	95	-	110	ns
		V _{CC} = 4.5 V	-	7	15	-	19	-	22	ns
		V _{CC} = 6.0 V	-	6	13	-	16	-	19	ns

Table 7. Dynamic characteristics ...continuedGND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 12](#)

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_w	pulse width	CP input HIGH or LOW; see Figure 7								
		$V_{CC} = 2.0$ V	80	17	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	6	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	5	-	17	-	20	-	ns
		$\overline{PL}$ input LOW; see Figure 8								
		$V_{CC} = 2.0$ V	80	14	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	5	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	4	-	17	-	20	-	ns
t_{rec}	recovery time	$\overline{PL}$ to CP, $\overline{CE}$; see Figure 8								
		$V_{CC} = 2.0$ V	100	22	-	125	-	150	-	ns
		$V_{CC} = 4.5$ V	20	8	-	25	-	30	-	ns
		$V_{CC} = 6.0$ V	17	6	-	21	-	26	-	ns
t_{su}	set-up time	DS to CP, $\overline{CE}$; see Figure 10								
		$V_{CC} = 2.0$ V	80	11	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	4	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	3	-	17	-	20	-	ns
		$\overline{CE}$ to CP and CP to $\overline{CE}$; see Figure 10								
		$V_{CC} = 2.0$ V	80	17	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	6	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	5	-	17	-	20	-	ns
		Dn to $\overline{PL}$; see Figure 11								
		$V_{CC} = 2.0$ V	80	22	-	100	-	120	-	ns
		$V_{CC} = 4.5$ V	16	8	-	20	-	24	-	ns
		$V_{CC} = 6.0$ V	14	6	-	17	-	20	-	ns
t_h	hold time	DS to CP, $\overline{CE}$ and Dn to $\overline{PL}$; see Figure 10								
		$V_{CC} = 2.0$ V	5	6	-	5	-	5	-	ns
		$V_{CC} = 4.5$ V	5	2	-	5	-	5	-	ns
		$V_{CC} = 6.0$ V	5	2	-	5	-	5	-	ns
		$\overline{CE}$ to CP and CP to $\overline{CE}$; see Figure 10								
		$V_{CC} = 2.0$ V	5	–17	-	5	-	5	-	ns
		$V_{CC} = 4.5$ V	5	–6	-	5	-	5	-	ns
		$V_{CC} = 6.0$ V	5	–5	-	5	-	5	-	ns

Table 7. Dynamic characteristics ...continuedGND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 12](#)

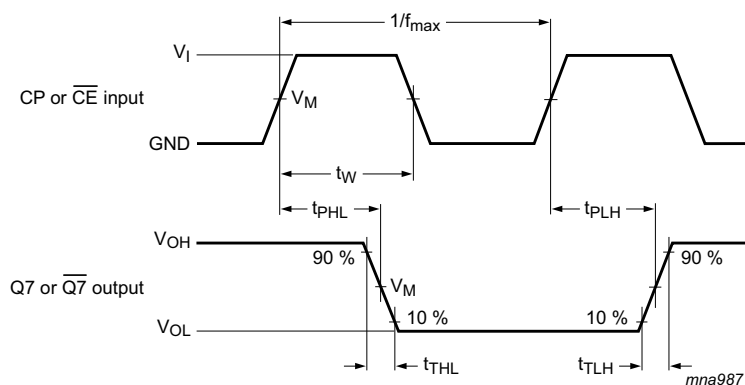
Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$f_{\max}$	maximum frequency	CP input; see Figure 7								
		$V_{CC} = 2.0$ V	6	17	-	5	-	4	-	MHz
		$V_{CC} = 4.5$ V	30	51	-	24	-	20	-	MHz
		$V_{CC} = 6.0$ V	35	61	-	28	-	24	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	56	-	-	-	-	-	MHz
C_{PD}	power dissipation capacitance	per package; $V_I = \text{GND to } V_{CC}$ [3]	-	35	-	-	-	-	-	pF
74HCT165										
t_{pd}	propagation delay	$\overline{CE}$, CP to Q7, $\overline{Q7}$; see Figure 7 [1]								
		$V_{CC} = 4.5$ V	-	17	34	-	43	-	51	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	14	-	-	-	-	-	ns
		$\overline{PL}$ to Q7, $\overline{Q7}$; see Figure 8								
		$V_{CC} = 4.5$ V	-	20	40	-	50	-	60	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	17	-	-	-	-	-	ns
		D7 to Q7, $\overline{Q7}$; see Figure 9								
		$V_{CC} = 4.5$ V	-	14	28	-	35	-	42	ns
t_t	transition time	$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	11	-	-	-	-	-	ns
t_W	pulse width	Q7, $\overline{Q7}$ output; see Figure 7 [2]								
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
		CP input; see Figure 7								
		$V_{CC} = 4.5$ V	16	6	-	20	-	24	-	ns
t_{rec}	recovery time	$\overline{PL}$ input; see Figure 8								
		$V_{CC} = 4.5$ V	20	9	-	25	-	30	-	ns
t_{su}	set-up time	$\overline{PL}$ to CP, $\overline{CE}$; see Figure 8								
		$V_{CC} = 4.5$ V	20	8	-	25	-	30	-	ns
t_{su}	set-up time	DS to CP, $\overline{CE}$; see Figure 10								
		$V_{CC} = 4.5$ V	20	2	-	25	-	30	-	ns
		$\overline{CE}$ to CP and CP to $\overline{CE}$; see Figure 10								
		$V_{CC} = 4.5$ V	20	7	-	25	-	30	-	ns
		Dn to $\overline{PL}$; see Figure 11								
		$V_{CC} = 4.5$ V	20	10	-	25	-	30	-	ns
t_h	hold time	DS to CP, $\overline{CE}$ and Dn to $\overline{PL}$; see Figure 10								
		$V_{CC} = 4.5$ V	7	-1	-	9	-	11	-	ns
		$\overline{CE}$ to CP and CP to $\overline{CE}$; see Figure 10								
		$V_{CC} = 4.5$ V	0	-7	-	0	-	0	-	ns

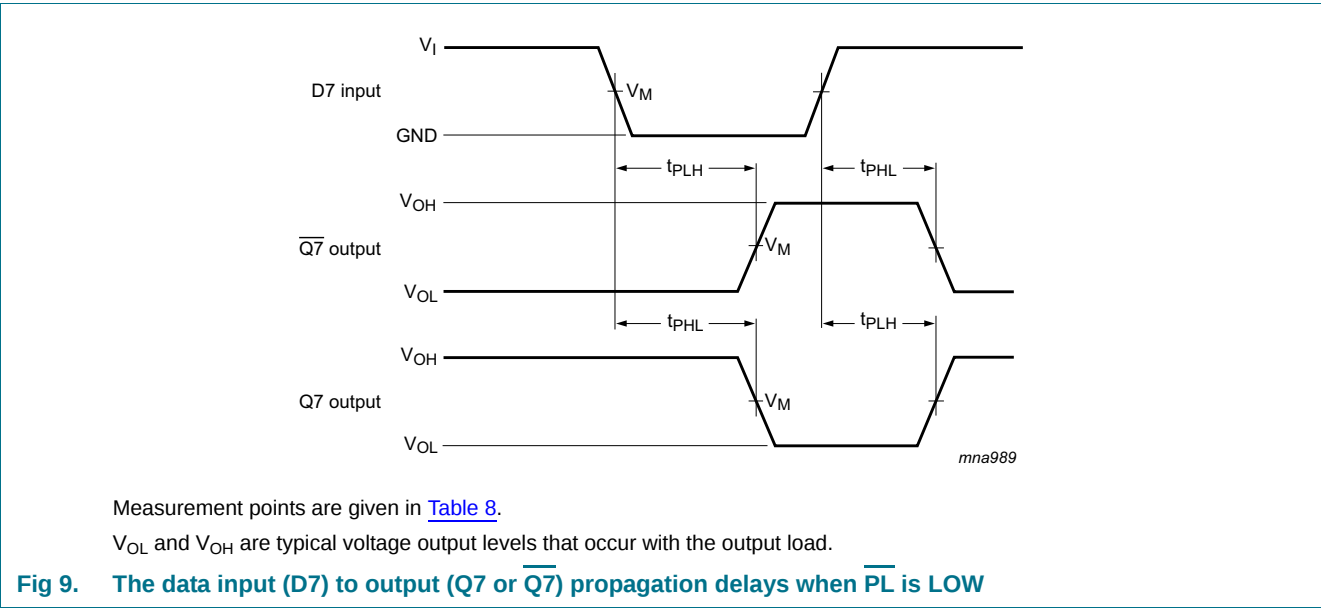
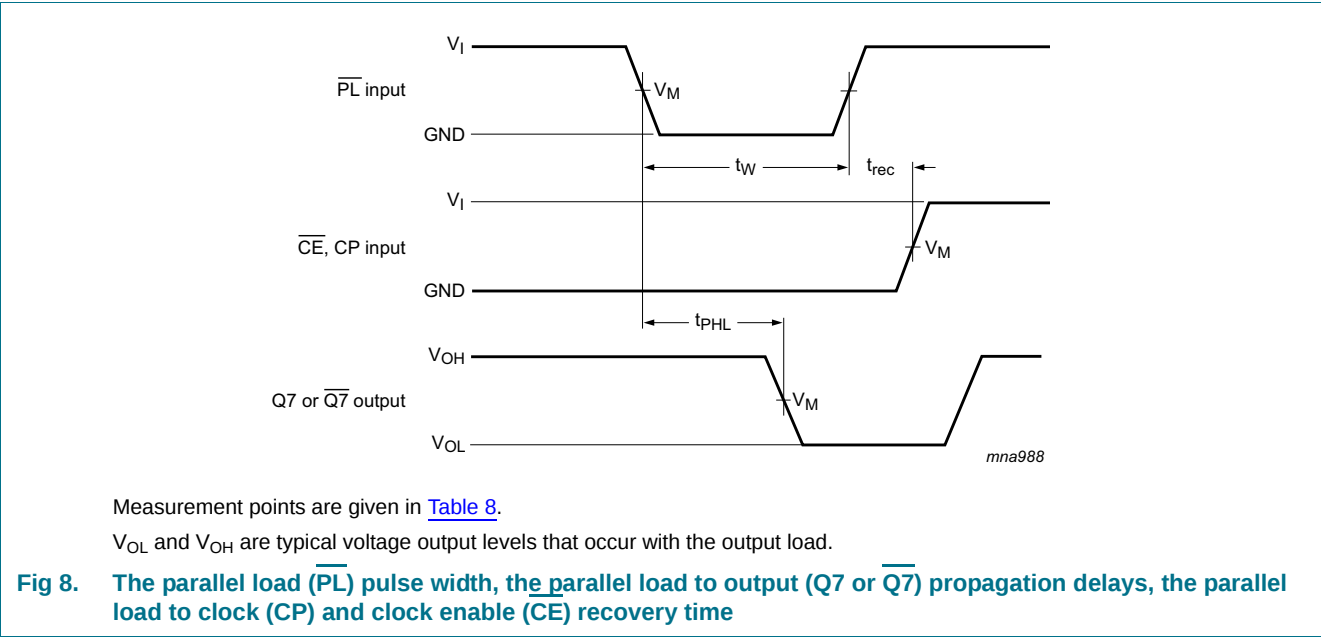
Table 7. Dynamic characteristics ...continuedGND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit, see [Figure 12](#)

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$f_{\max}$	maximum frequency	CP input; see Figure 7								
		$V_{CC} = 4.5$ V	26	44	-	21	-	17	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	48	-	-	-	-	-	MHz
C_{PD}	power dissipation capacitance	per package; $V_I = \text{GND to } V_{CC} - 1.5$ V [3]	-	35	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PHL} and t_{PLH} .[2] t_t is the same as t_{THL} and t_{TLH} .[3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW). $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; f_o = output frequency in MHz; $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs; C_L = output load capacitance in pF; V_{CC} = supply voltage in V.

12. Waveforms

Measurement points are given in [Table 8](#). V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.**Fig 7. The clock (CP) or clock enable (CE) to output (Q7 or Q7) propagation delays, the clock pulse width, the maximum clock frequency and the output transition times**



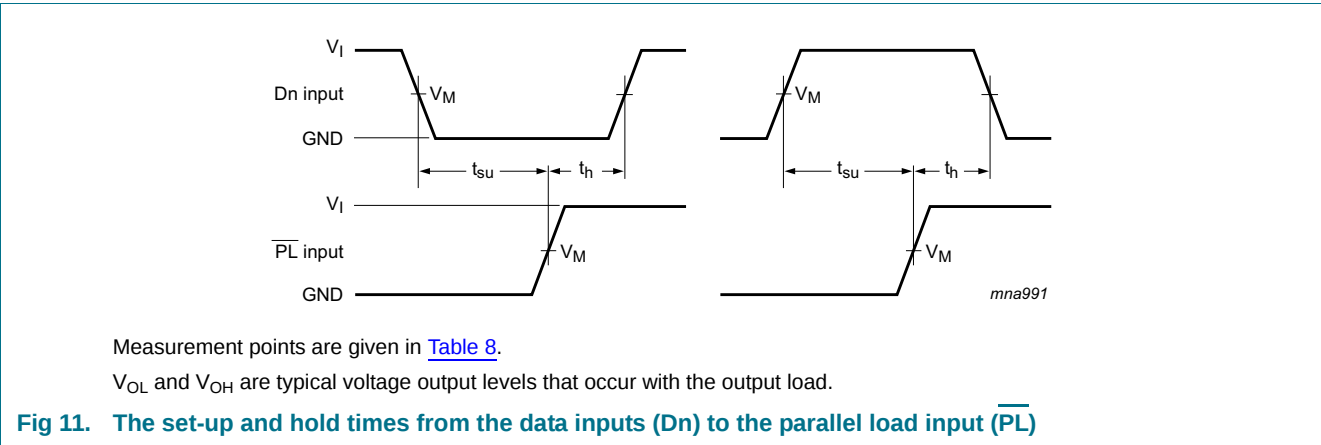
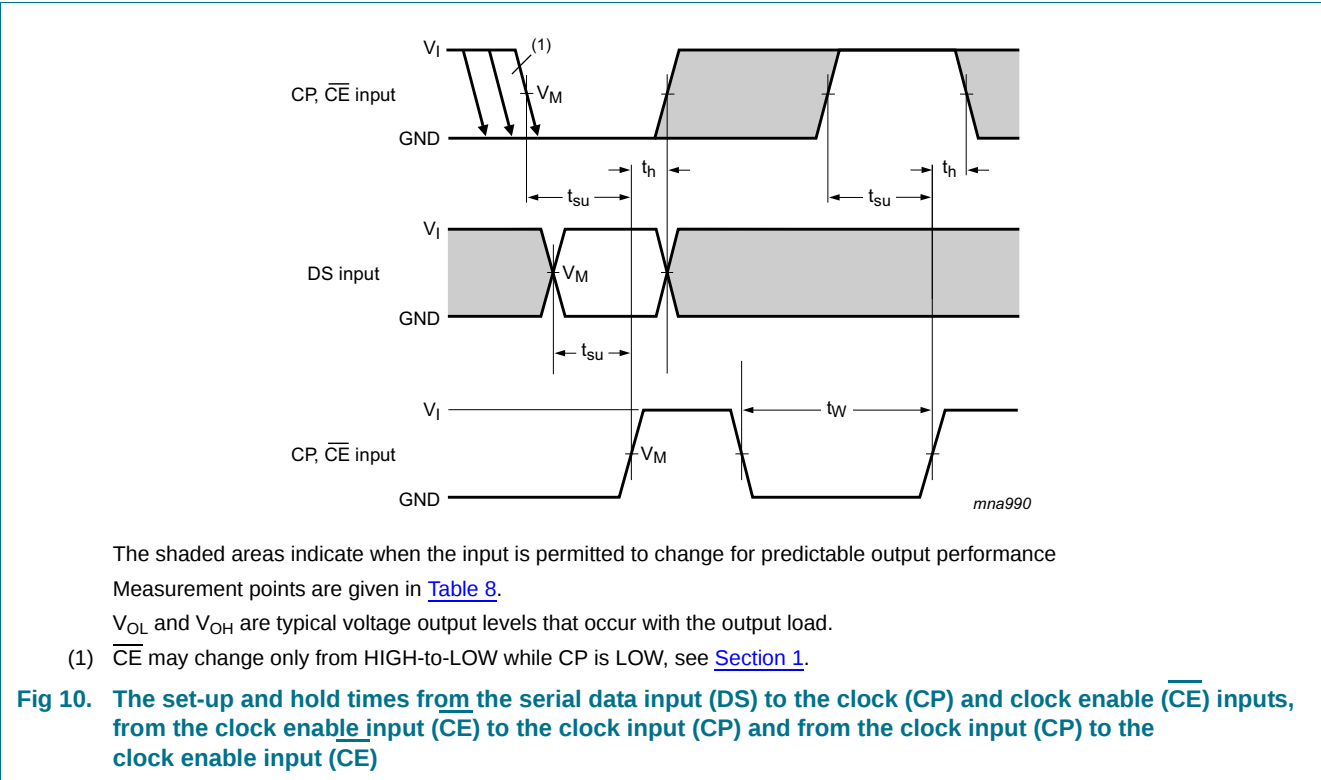


Table 8. Measurement points

Type	Input		Output
	V_I	V_M	V_M
74HC165	V_{CC}	$0.5V_{CC}$	$0.5V_{CC}$
74HCT165	3 V	1.3 V	1.3 V

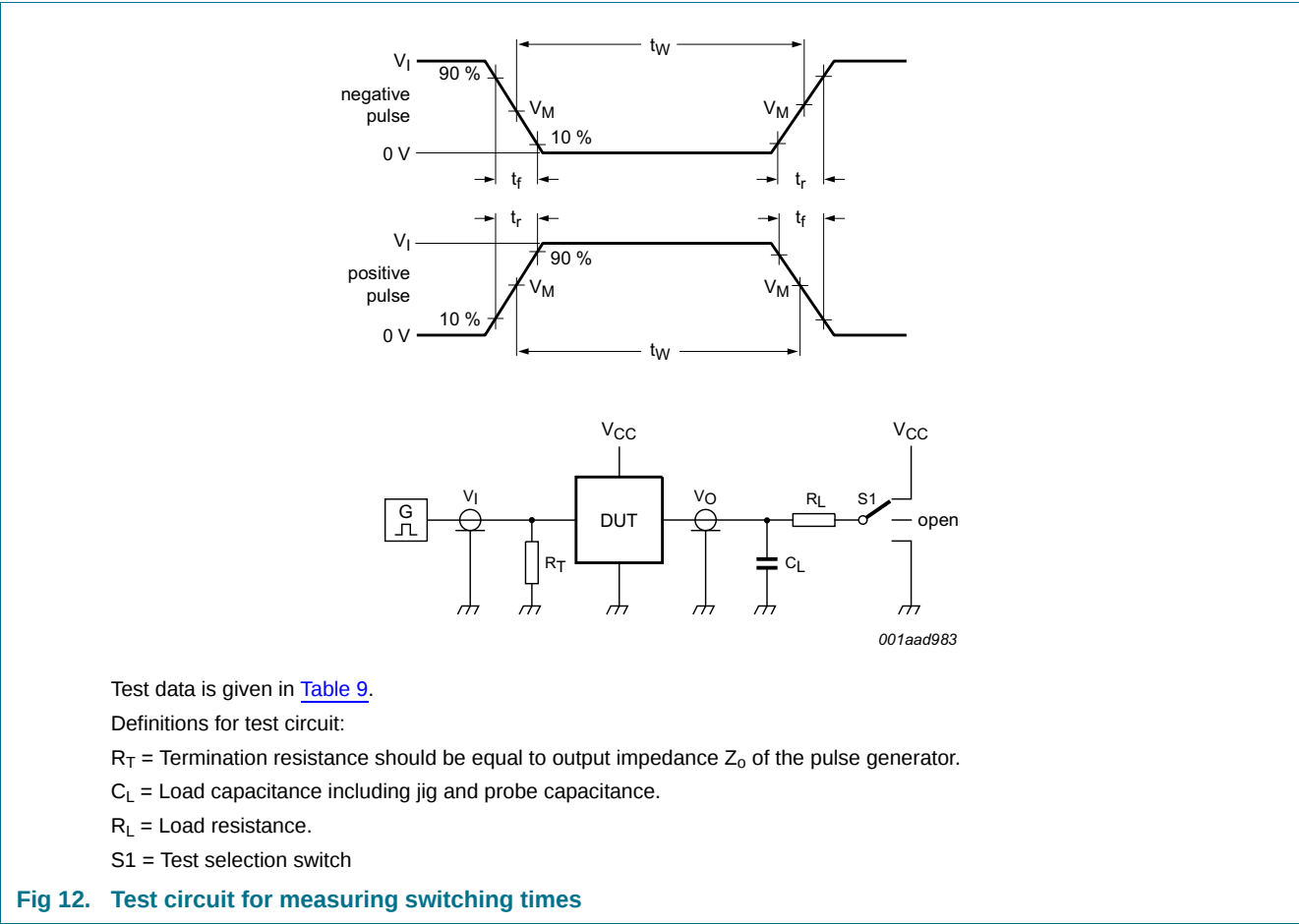


Table 9. Test data

Type	Input		Load		S1 position
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}
74HC165	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open
74HCT165	3 V	6 ns	15 pF, 50 pF	1 k Ω	open

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

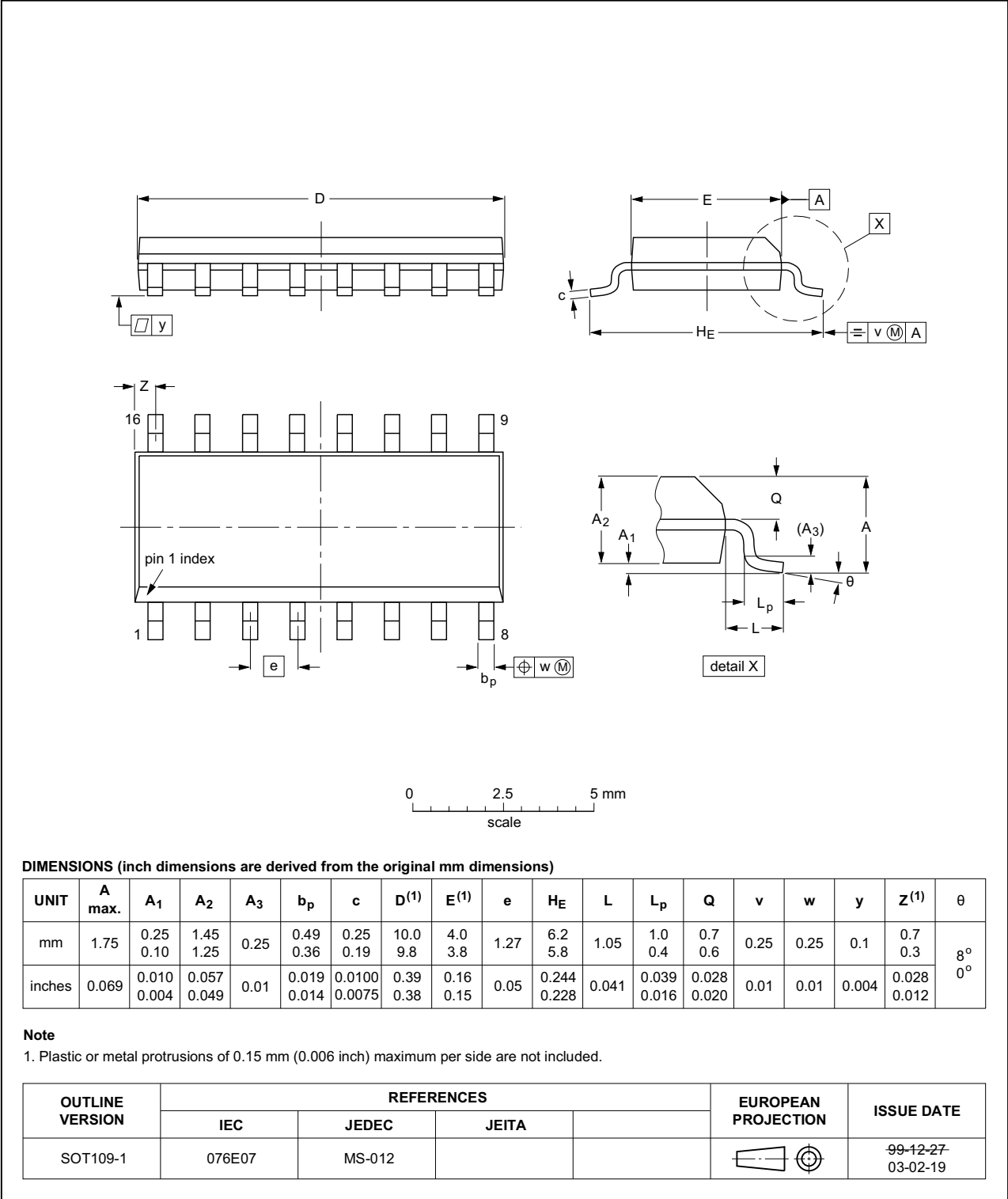


Fig 13. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

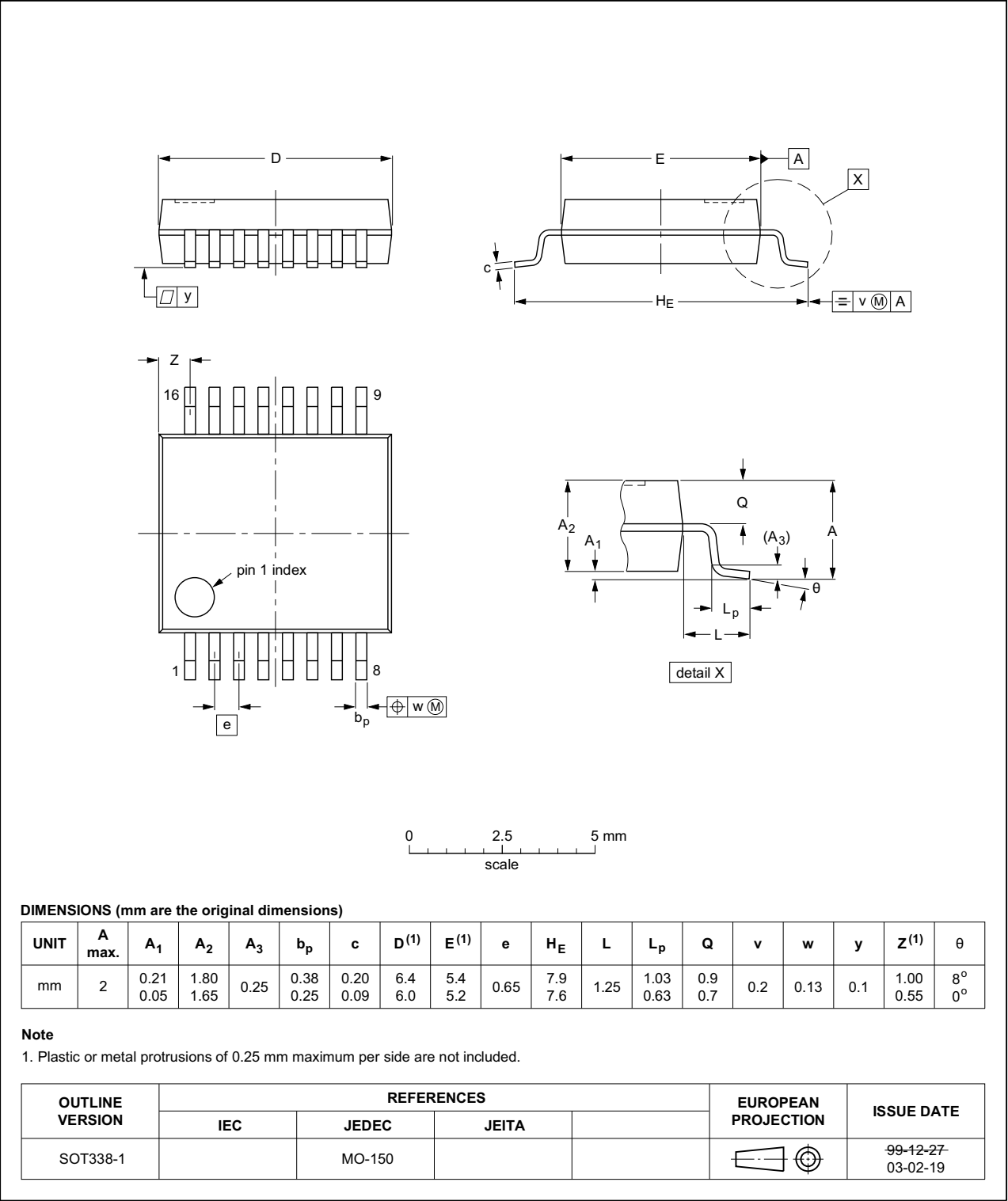
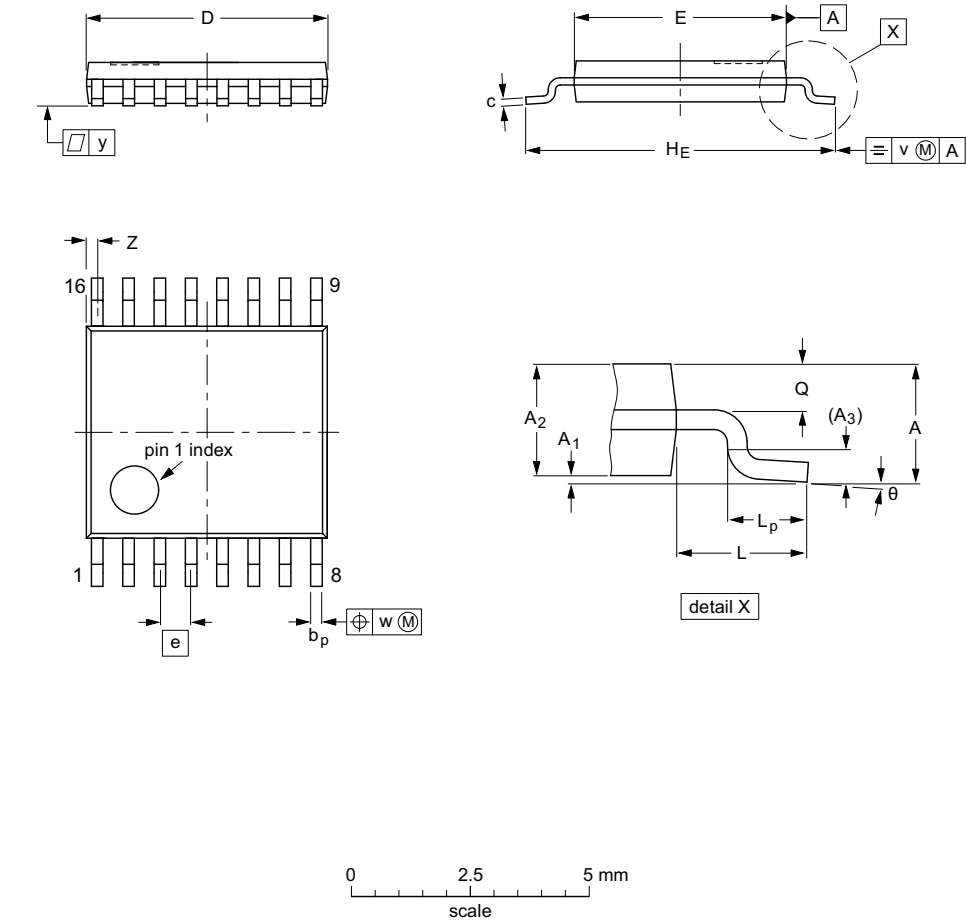


Fig 14. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				-99-12-27- 03-02-18

Fig 15. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm SOT763-1

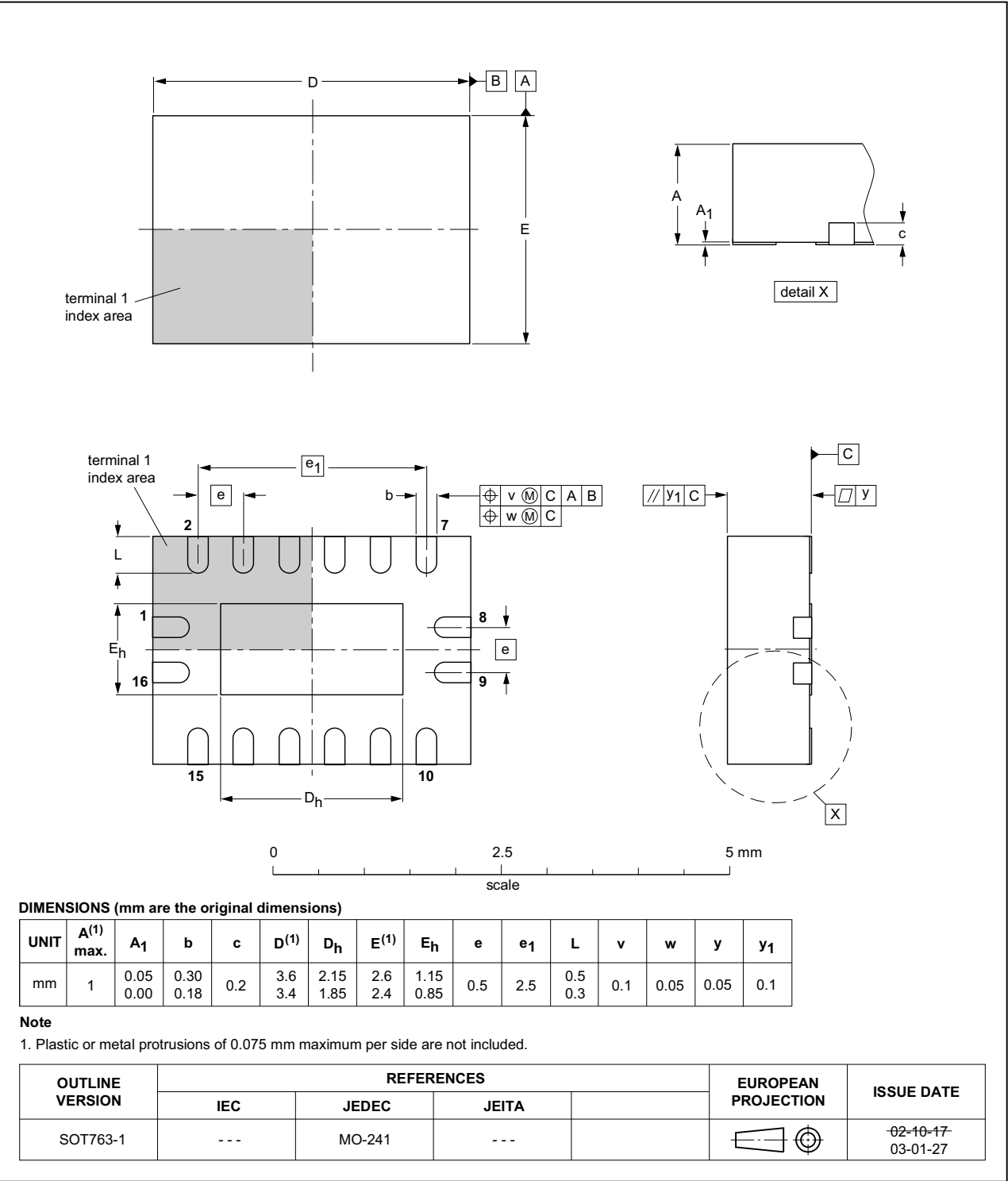


Fig 16. Package outline SOT763-1 (DHVQFN16)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT165 v.4	20151228	Product data sheet	-	74HC_HCT165 v.3
Modifications:	Type numbers 74HC165N and 74HCT165N (SOT38-4) removed.			
74HC_HCT165 v.3	20080314	Product data sheet	-	74HC_HCT165_CNV v.2
Modifications:	- The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. - Legal texts have been adapted to the new company name where appropriate. - Package SOT763-1 (DHVQFN16) added to Section 4 “Ordering information” and Section 13 “Package outline”. - Family data added, see Section 10 “Static characteristics”			
74HC_HCT165_CNV v.2	December 1990	Product specification	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Date of release: 28 December 2015

Document identifier: 74HC_HCT165

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